

# **No-Clean Liquid Rework Flux**

## **Features:**

- Passes SIR in Raw State

- Halide-Free

- Excellent Wetting

- Low-Residue

- Wide Process Window

- Extremely Safe for Rework

# **Description:**

AIM's NC Flux Pen contains a low- to medium-solids, no-clean liquid flux formulated to leave minimal postprocess residues that are pin testable without cleaning. NC Flux offers an excellent activity level with good performance on bare copper, solder coated and organic coated PWBs, leaving negligible post-process residues that are non-conductive and do not require post-process cleaning. NC Flux is safe to be left on the circuit board and passes SIR in the raw state.

### **Cleaning:**

NC Flux can be cleaned, if necessary, with saponified water or an appropriate solvent cleaner. Please refer to the AIM No-Clean-Cleaner Matrix for a list of suitable cleaning materials.

## Handling:

- NC Flux has an unopened shelf life of 1 year when stored at room temperature.
- Do not store near fire or flame.
- Keep away from sunlight as it may degrade product.
- Reseal any opened containers.

### Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

### **Physical Properties:**

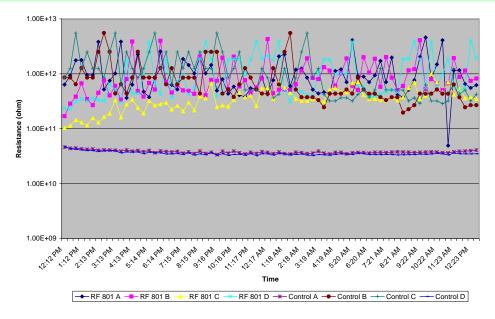
| Parameter      | Value                      |  |
|----------------|----------------------------|--|
| J-STD-004      | ROL0                       |  |
| Visual         | Light Yellow               |  |
| Odor           | Aromatic (Slightly)        |  |
| Solids Content | 3.57%                      |  |
| Acid Number    | 12.82 mg KOH per gram flux |  |

| Parameter               | Value            |
|-------------------------|------------------|
| Specific Gravity        | 0.79 (water = 1) |
| Flash Point             | 12°C             |
| Boiling Point           | 80°C             |
| pH (1% solution /water) | Acidic           |

# **Corrosion Testing:**

| Parameter                            | Requirements      | Results |
|--------------------------------------|-------------------|---------|
| Copper Mirror (24 hrs @ 25°C, 50%RH) | IPC-TM-650-2.3.32 | Low     |
| Halide Test (Silver Chromate)        | IPC-TM-650-2.2.33 | Pass    |

#### **Raw Flux Surface Insulation Resistance Results:**



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